



P-Channel Enhancement-Mode Vertical DMOS Power FETs

Ordering Information

BV _{DSS} / BV _{DGS}	R _{DS(ON)} (max)	I _{DI(ON)} (min)	Order Number / Package			
			TO-3	TO-39	TO-220	DICE
-160V	5Ω	-1.5A	VP1116N1	VP1116N2	VP1116N5	VP1116ND
-200V	5Ω	-1.5A	VP1120N1	VP1120N2	VP1120N5	VP1120ND

Features

- Freedom from secondary breakdown
- Low power drive requirement
- Ease of paralleling
- Low C_{ISS} and fast switching speeds
- Excellent thermal stability
- Integral Source-Drain diode
- High input impedance and high gain
- Complementary N- and P-Channel devices

Applications

- Motor control
- Convertors
- Amplifiers
- Switches
- Power supply circuits
- Driver (Relays, Hammers, Solenoids, Lamps, Memories, Displays, Bipolar Transistors, etc.)

Absolute Maximum Ratings

Drain-to-Source Voltage	BV _{DSS}
Drain-to-Gate Voltage	BV _{DGS}
Gate-to-Source Voltage	± 20V
Operating and Storage Temperature	-55°C to +150°C
Soldering Temperature*	300°C

*Distance of 1.6 mm from case for 10 seconds.

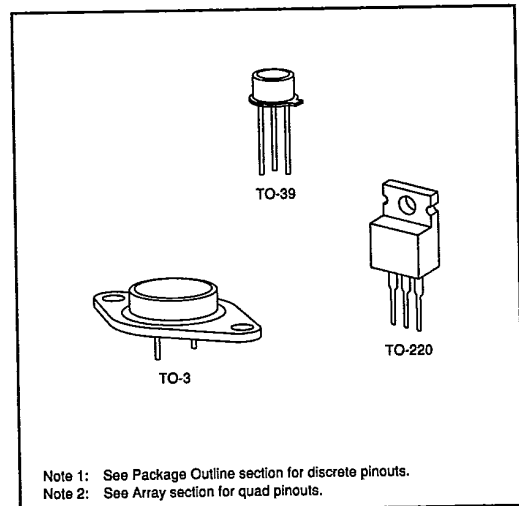
Advanced DMOS Technology

These enhancement-mode (normally-off) power transistors utilize a vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces devices with the power handling capabilities of bipolar transistors and with the high input impedance and negative temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, these devices are free from thermal runaway and thermally-induced secondary breakdown.

Supertex Vertical DMOS Power FETs are ideally suited to a wide range of switching and amplifying applications where high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Package Options

(Notes 1 and 2)



Thermal Characteristics

7-39-19

Package	I_D (continuous)*	I_D (pulsed)*	Power Dissipation @ $T_C = 25^\circ\text{C}$	θ_{JA} $^\circ\text{C/W}$	θ_{JC} $^\circ\text{C/W}$	I_{DR}	I_{DRM}^*
TO-3	-2.5A	-7.5A	75W	50	1.6	-2.5A	-7.5A
TO-39	-0.8A	-3A	6W	125	20.8	-0.8A	-3A
TO-220	-1.8A	-7A	45W	70	2.7	-1.8A	-7A

* I_D (continuous) is limited by max rated T_J .

Electrical Characteristics (@ 25°C unless otherwise specified)

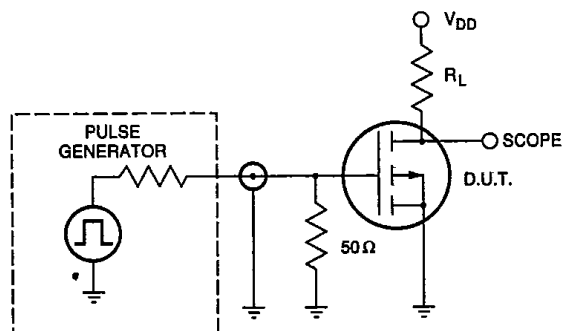
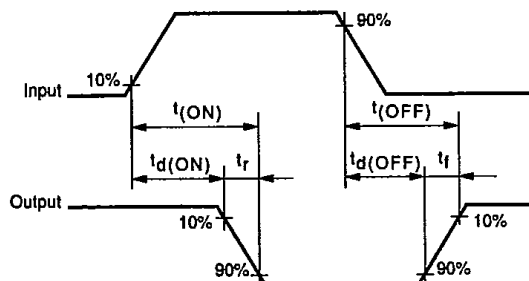
(Notes 1 and 2)

Symbol	Parameter	Min	Typ	Max	Unit	Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	VP1120	-200		V	$I_D = -5\text{mA}, V_{GS} = 0$
		VP1116	-160			
$V_{GS(th)}$	Gate Threshold Voltage	-1.5		-3.5	V	$V_{GS} = V_{DS}, I_D = -5\text{mA}$
$\Delta V_{GS(th)}$	Change in $V_{GS(th)}$ with Temperature		-3.5	-6	mV/ $^\circ\text{C}$	$I_D = -5\text{mA}, V_{GS} = V_{DS}$
I_{GSS}	Gate Body Leakage			-100	nA	$V_{GS} = \pm 20\text{V}, V_{DS} = 0$
I_{DSS}	Zero Gate Voltage Drain Current			-50	μA	$V_{GS} = 0, V_{DS} = \text{Max Rating}$
				-10	mA	$V_{GS} = 0, V_{DS} = 0.8 \text{ Max Rating}$ $T_A = 125^\circ\text{C}$
$I_{D(ON)}$	ON-State Drain Current	0.5	1.5		A	$V_{GS} = -5\text{V}, V_{DS} = -25\text{V}$
		1.5	4			$V_{GS} = -10\text{V}, V_{DS} = -25\text{V}$
$R_{DS(ON)}$	Static Drain-to-Source ON-State Resistance		3.3	7	Ω	$V_{GS} = -5\text{V}, I_D = -0.5\text{A}$
			3	5		$V_{GS} = -10\text{V}, I_D = -1.0\text{A}$
$\Delta R_{DS(ON)}$	Change in $R_{DS(ON)}$ with Temperature		0.8	1.2	%/ $^\circ\text{C}$	$I_D = -1.0\text{A}, V_{GS} = -10\text{V}$
G_{FS}	Forward Transconductance	0.5	0.75		S	$V_{DS} = -25\text{V}, I_D = -1.0\text{A}$
C_{ISS}	Input Capacitance		300	350	pF	$V_{GS} = 0, V_{DS} = -25\text{V}$ $f = 1 \text{ MHz}$
C_{OSS}	Common Source Output Capacitance		60	80		
C_{RSS}	Reverse Transfer Capacitance		10	25		
$t_{d(ON)}$	Turn-ON Delay Time		8	25	ns	$V_{DD} = -25\text{V}$ $I_D = -1.0\text{A}$ $R_S = 50\Omega$
t_r	Rise Time		4	20		
$t_{d(OFF)}$	Turn-OFF Delay Time		24	40		
t_f	Fall Time		8	20		
V_{SD}	Diode Forward Voltage Drop		-1.2	-2.0		
t_{rr}	Reverse Recovery Time		350		ns	$I_{SD} = -1.0\text{A}, V_{GS} = 0$

Note 1: All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300 μs pulse, 2% duty cycle.)

Note 2: All A.C. parameters sample tested.

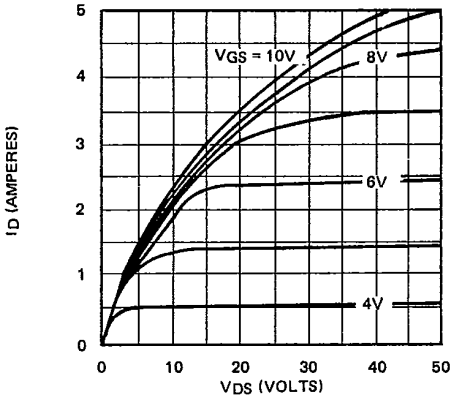
Switching Waveforms and Test Circuit



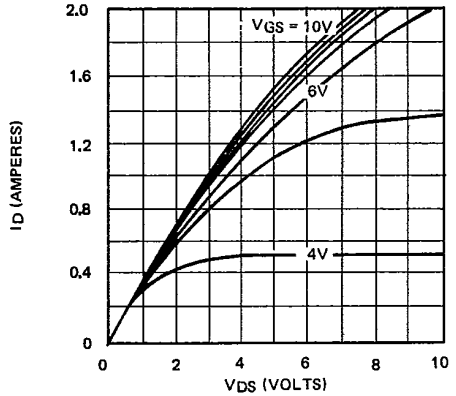
Typical Performance Curves

T.39-19

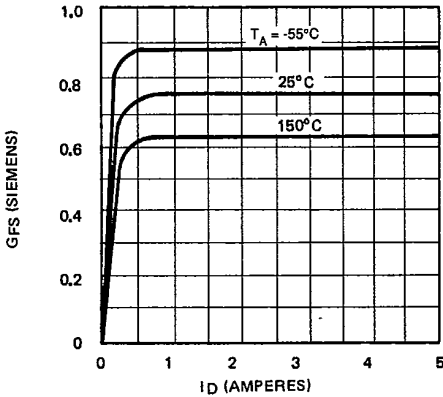
Output Characteristics



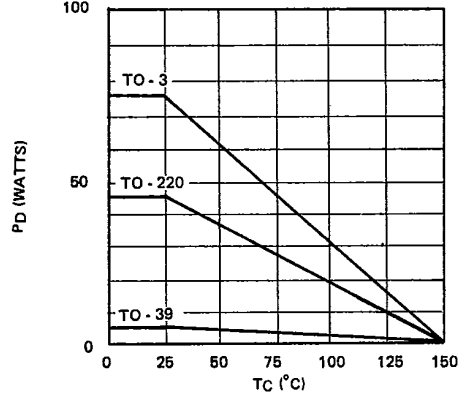
Saturation Characteristics



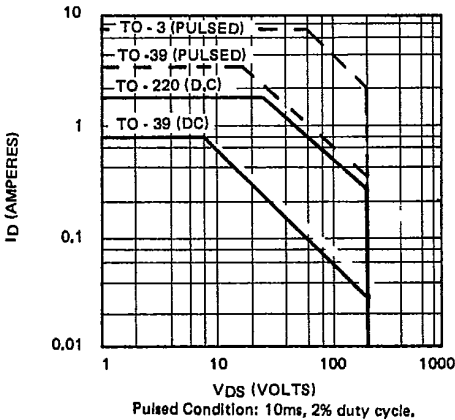
Transconductance Vs. Drain Current



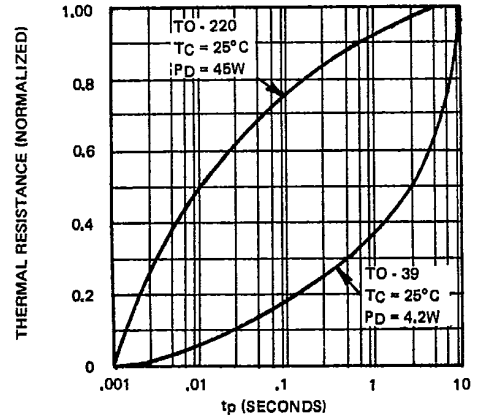
Power Dissipation Vs. Case Temperature



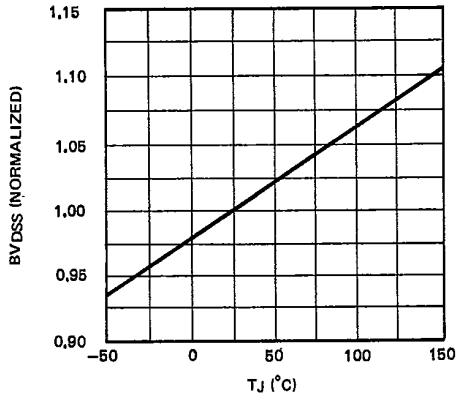
Maximum Rated Safe Operating Area



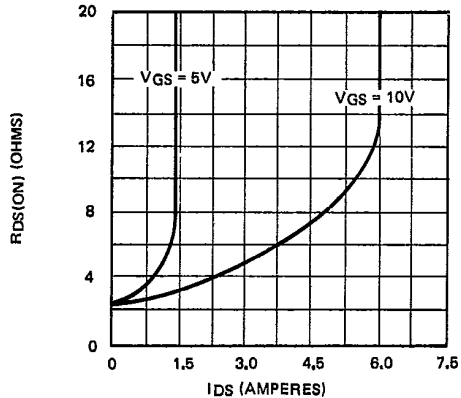
Thermal Response Characteristics



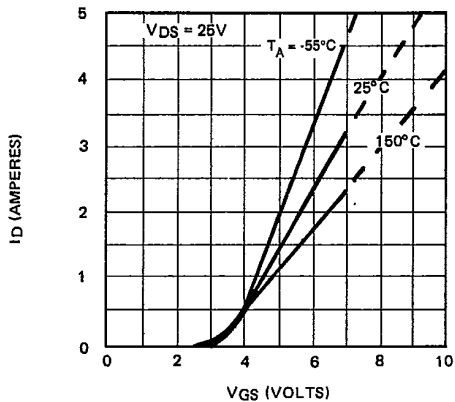
BV_{DSS} Variation with Temperature



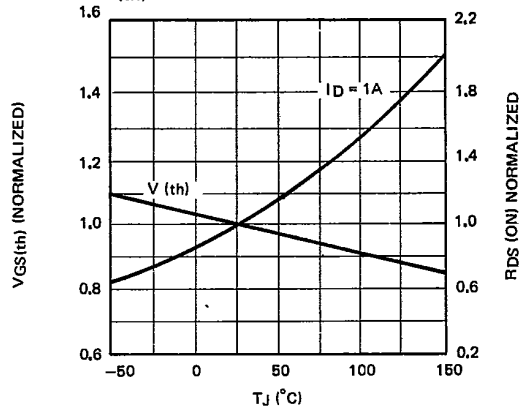
ON - Resistance Vs. Drain Current



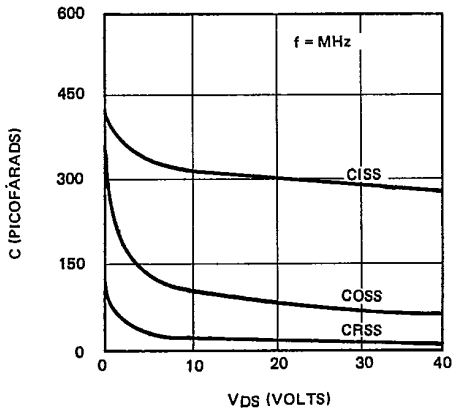
Transfer Characteristics



V(th) and R_{DS} Variation with Temperature



Capacitance Vs. Drain-to-Source Voltage



Gate Drive Dynamic Characteristics

